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Understanding Embedded - Microprocessors

Embedded microprocessors are specialized computing chips designed to perform specific tasks within an embedded system. Unlike general-purpose microprocessors found in personal computers, embedded microprocessors are tailored for dedicated functions within larger systems, offering optimized performance, efficiency, and reliability. These microprocessors are integral to the operation of countless electronic devices, providing the computational power necessary for controlling processes, handling data, and managing communications.

Applications of Embedded - Microprocessors

Embedded microprocessors are utilized across a broad spectrum of applications, making them indispensable in

Details	
Product Status	Obsolete
Core Processor	MPC8xx
Number of Cores/Bus Width	1 Core, 32-Bit
Speed	133MHz
Co-Processors/DSP	Communications; CPM
RAM Controllers	DRAM
Graphics Acceleration	No
Display & Interface Controllers	-
Ethernet	10Mbps (2), 10/100Mbps (2)
SATA	-
USB	USB 2.0 (1)
Voltage - I/O	3.3V
Operating Temperature	-40°C ~ 100°C (TA)
Security Features	-
Package / Case	357-BBGA
Supplier Device Package	357-PBGA (25x25)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/kmpc880cvr133

1 Overview

The MPC885/MPC880 is a versatile single-chip integrated microprocessor and peripheral combination that can be used in a variety of controller applications and communications and networking systems. The MPC885/MPC880 provides enhanced ATM functionality, an additional fast Ethernet controller, a USB, and an encryption block.

Table 1 shows the functionality supported by MPC885/MPC880.

Table 1. MPC885 Family

Part	Cache (Kbytes)		Ethernet		SCC	SMC	USB	ATM Support	Security Engine
	I Cache	D Cache	10BaseT	10/100					
MPC885	8	8	Up to 3	2	3	2	1	Serial ATM and UTOPIA interface	Yes
MPC880	8	8	Up to 2	2	2	2	1	Serial ATM and UTOPIA interface	No

2 Features

The MPC885/MPC880 is comprised of three modules that each use the 32-bit internal bus: a MPC8xx core, a system integration unit (SIU), and a communications processor module (CPM).

The following list summarizes the key MPC885/MPC880 features:

- Embedded MPC8xx core up to 133 MHz
- Maximum frequency operation of the external bus is 80 MHz (in 1:1 mode)
  - — The 133-MHz core frequency supports 2:1 mode only.
  - — The 66-/80-MHz core frequencies support both the 1:1 and 2:1 modes.
- Single-issue, 32-bit core (compatible with the Power Architecture definition) with thirty-two 32-bit general-purpose registers (GPRs)
  - — The core performs branch prediction with conditional prefetch and without conditional execution.
  - — 8-Kbyte data cache and 8-Kbyte instruction cache (see Table 1)
    - – Instruction cache is two-way, set-associative with 256 sets in 2 blocks
    - – Data cache is two-way, set-associative with 256 sets
    - – Cache coherency for both instruction and data caches is maintained on 128-bit (4-word) cache blocks.
    - – Caches are physically addressed, implement a least recently used (LRU) replacement algorithm, and are lockable on a cache block basis.
  - — MMUs with 32-entry TLB, fully associative instruction and data TLBs
  - — MMUs support multiple page sizes of 4, 16, and 512 Kbytes, and 8 Mbytes; 16 virtual address spaces and 16 protection groups
  - — Advanced on-chip emulation debug mode

- — Periodic interrupt timer (PIT)
- — Clock synthesizer
- — Decrementer and time base
- — Reset controller
- — IEEE Std 1149.1™ test access port (JTAG)

- Security engine is optimized to handle all the algorithms associated with IPsec, SSL/TLS, SRTP, IEEE Std 802.11i™, and iSCSI processing. Available on the MPC885, the security engine contains a crypto-channel, a controller, and a set of crypto hardware accelerators (CHAs). The CHAs are:
  - — Data encryption standard execution unit (DEU)
    - – DES, 3DES
    - – Two key (K1, K2, K1) or three key (K1, K2, K3)
    - – ECB and CBC modes for both DES and 3DES
  - — Advanced encryption standard unit (AESU)
    - – Implements the Rijndael symmetric key cipher
    - – ECB, CBC, and counter modes
    - – 128-, 192-, and 256- bit key lengths
  - — Message digest execution unit (MDEU)
    - – SHA with 160- or 256-bit message digest
    - – MD5 with 128-bit message digest
    - – HMAC with either algorithm
  - — Crypto-channel supporting multi-command descriptor chains
  - — Integrated controller managing internal resources and bus mastering
  - — Buffer size of 256 bytes for the DEU, AESU, and MDEU, with flow control for large data sizes
- Interrupts
  - — Six external interrupt request (IRQ) lines
  - — 12 port pins with interrupt capability
  - — 23 internal interrupt sources
  - — Programmable priority between SCCs
  - — Programmable highest priority request
- Communications processor module (CPM)
  - — RISC controller
  - — Communication-specific commands (for example, GRACEFUL STOP TRANSMIT, ENTER HUNT MODE, and RESTART TRANSMIT)
  - — Supports continuous mode transmission and reception on all serial channels
  - — 8-Kbytes of dual-port RAM
  - — Several serial DMA (SDMA) channels to support the CPM
  - — Three parallel I/O registers with open-drain capability

- 1.8-V core and 3.3-V I/O operation
- The MPC885/MPC880 comes in a 357-pin ball grid array (PBGA) package

The MPC885 block diagram is shown in Figure 1.

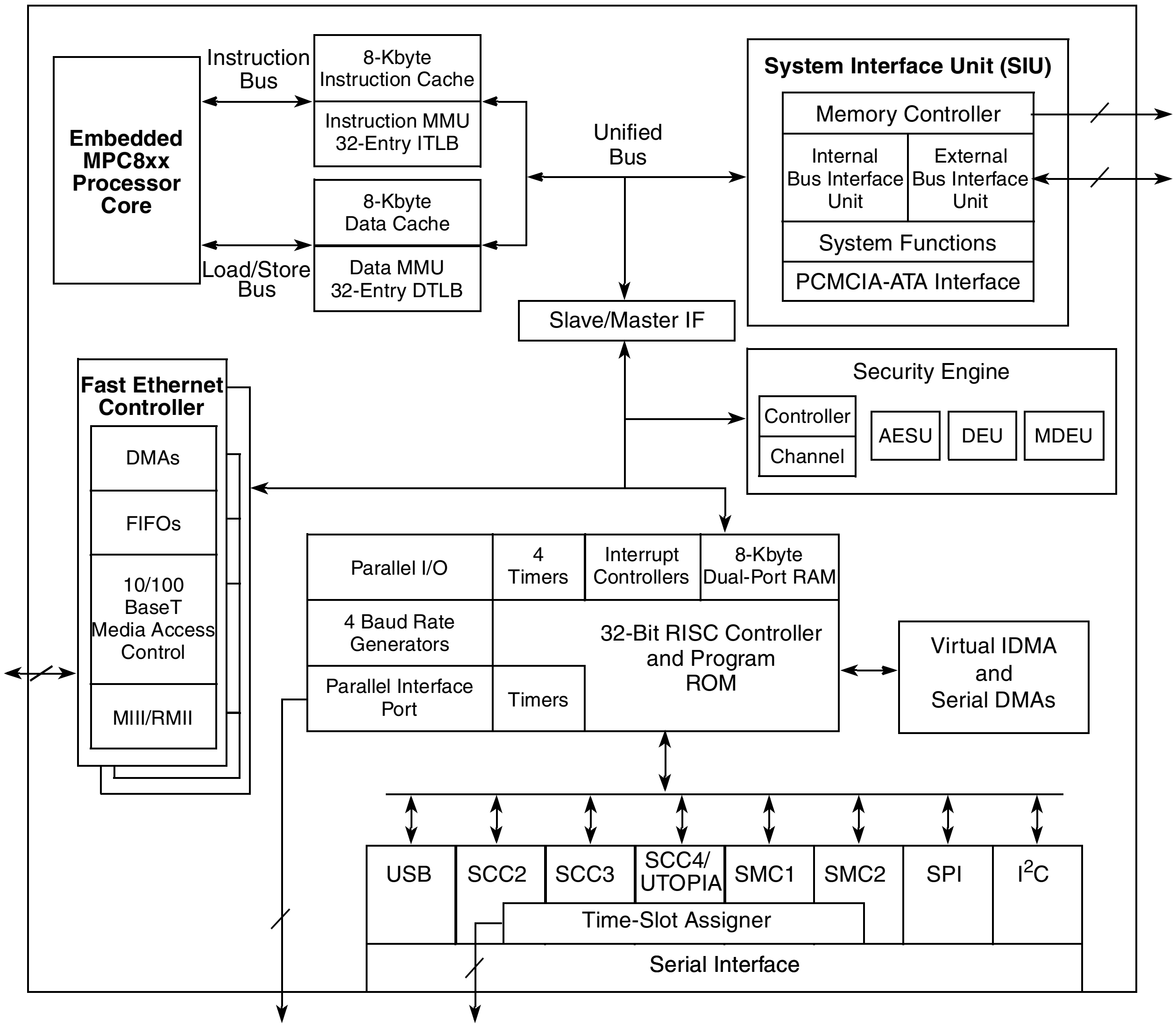


Figure 1. MPC885 Block Diagram

Table 6. DC Electrical Specifications (continued)

Characteristic	Symbol	Min	Max	Unit
Output high voltage, I_{OH} = –2.0 mA, except XTAL and open-drain pins	V_{OH}	2.4	—	V
Output low voltage I_{OL} = 2.0 mA (CLKOUT) I_{OL} = 3.2 mA[5] I_{OL} = 5.3 mA[6] I_{OL} = 7.0 mA (TXD1/PA14, TXD2/PA12) I_{OL} = 8.9 mA ($\overline{\text{TS}}$, $\overline{\text{TA}}$, $\overline{\text{TEA}}$, $\overline{\text{BI}}$, $\overline{\text{BB}}$, $\overline{\text{HRESET}}$, $\overline{\text{SRESET}}$)	V_{OL}	—	0.5	V

1 The difference between V_{DDL} and V_{DDSYN} cannot be more than 100 mV.

2 The signals PA[0:15], PB[14:31], PC[4:15], PD[3:15], PE(14:31), TDI, TDO, TCK, $\overline{\text{TRST}}$, TMS, MII1_TXEN, MII_MDIO are 5-V tolerant. The minimum voltage is still 2.0 V.

3 V_{IL}(max) for the I^2C interface is 0.8 V rather than the 1.5 V as specified in the I^2C standard.

4 Input capacitance is periodically sampled.

5 A(0:31), TSIZ0/$\overline{\text{REG}}$, TSIZ1, D(0:31), $\overline{\text{IRQ}}$(2:4), $\overline{\text{IRQ6}}$, RD/$\overline{\text{WR}}$, $\overline{\text{BURST}}$, IP_B(3:7), PA(0:11), PA13, PA15, PB(14:31), PC(4:15), PD(3:15), PE(14:31), MII1_CRS, MII_MDIO, MII1_TXEN, and MII1_COL.

6 $\overline{\text{BDIP/GPL\_B}}$(5), $\overline{\text{BR}}$, $\overline{\text{BG}}$, FRZ/$\overline{\text{IRQ6}}$, $\overline{\text{CS}}$(0:7), $\overline{\text{WE}}$(0:3), $\overline{\text{BS\_A}}$(0:3), $\overline{\text{GPL\_A0/GPL\_B0}}$, $\overline{\text{OE/GPL\_A1/GPL\_B1}}$, $\overline{\text{GPL\_A}}$(2:3)/$\overline{\text{GPL\_B}}$(2:3)/$\overline{\text{CS}}$(2:3), UPWAITA/$\overline{\text{GPL\_A4}}$, UPWAITB/$\overline{\text{GPL\_B4}}$, $\overline{\text{GPL\_A5}}$, ALE_A, $\overline{\text{CE1}}$_A, $\overline{\text{CE2}}$_A, OP(0:3), and BADDR(28:30).

7 Thermal Calculation and Measurement

For the following discussions, $P_D = (V_{DDL} \times I_{DDL}) + PI/O$, where PI/O is the power dissipation of the I/O drivers.

NOTE

The V_{DDSYN} power dissipation is negligible.

7.1 Estimation with Junction-to-Ambient Thermal Resistance

An estimation of the chip junction temperature, T_J, in °C can be obtained from the following equation:

$$T_J = T_A + (R_{\theta JA} \times P_D)$$

where:

T_A = ambient temperature (ºC)

$R_{\theta JA}$ = package junction-to-ambient thermal resistance (ºC/W)

P_D = power dissipation in package

The junction-to-ambient thermal resistance is an industry standard value that provides a quick and easy estimation of thermal performance. However, the answer is only an estimate; test cases have demonstrated that errors of a factor of two (in the quantity $T_J - T_A$) are possible.

Figure 10 provides the timing for the synchronous input signals.

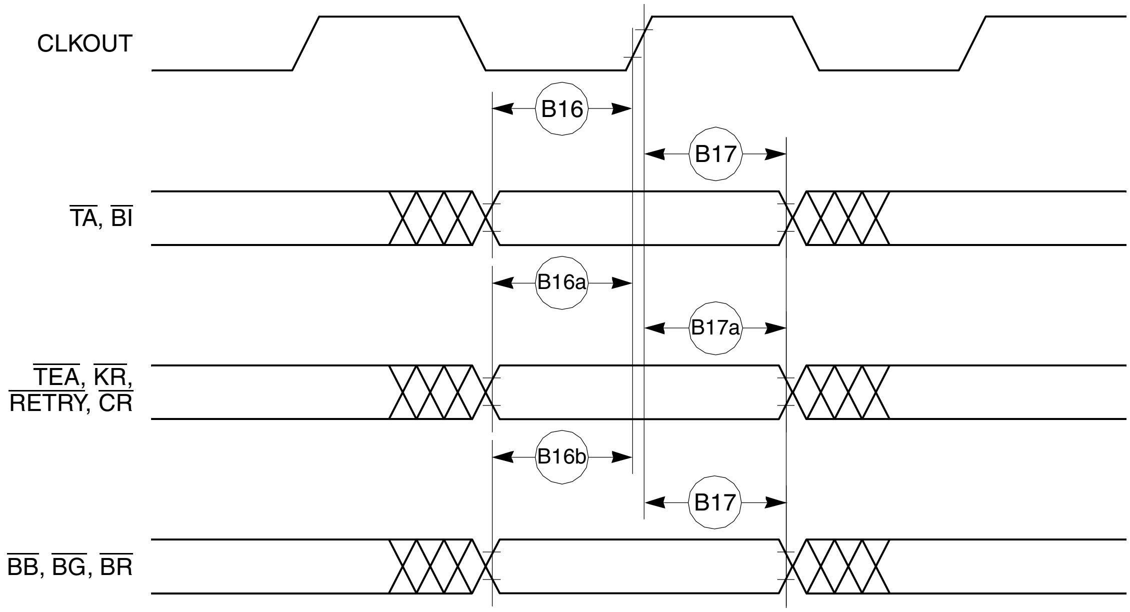


Figure 10. Synchronous Input Signals Timing

Figure 11 provides normal case timing for input data. It also applies to normal read accesses under the control of the user-programmable machine (UPM) in the memory controller.

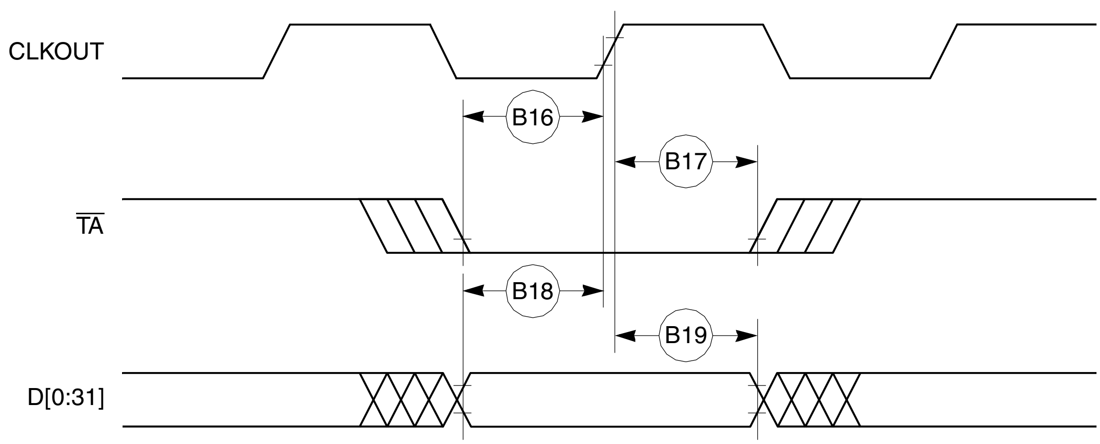


Figure 11. Input Data Timing in Normal Case

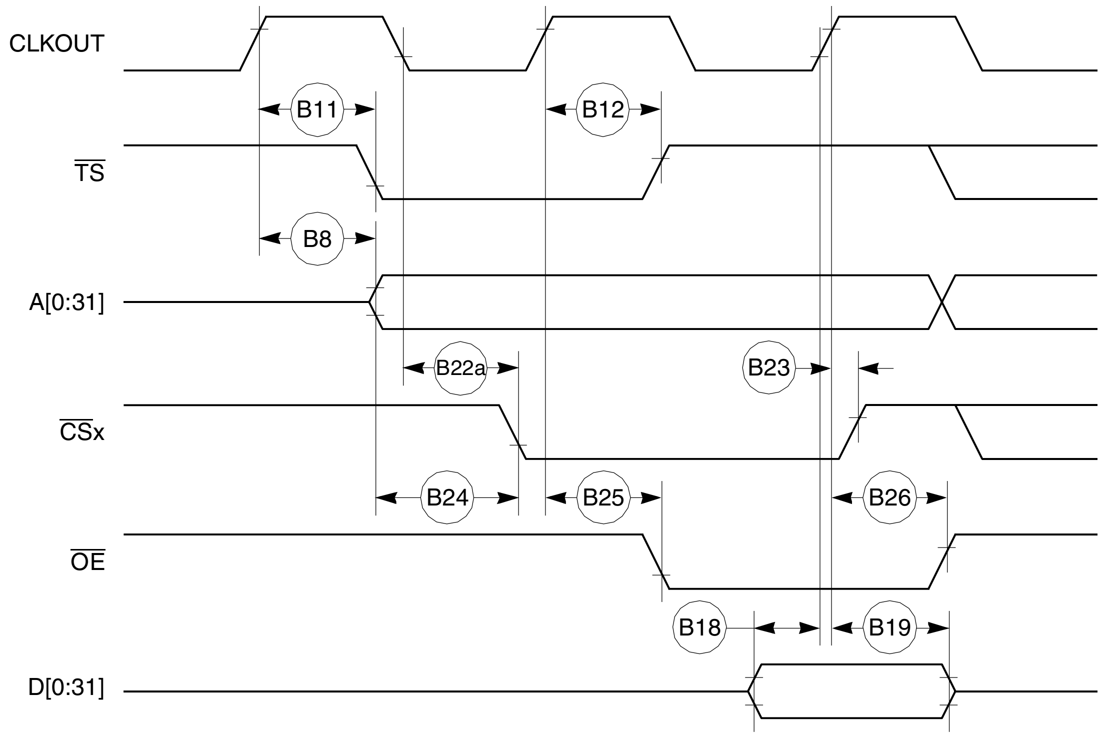


Figure 14. External Bus Read Timing (GPCM Controlled—TRLX = 0, ACS = 10)

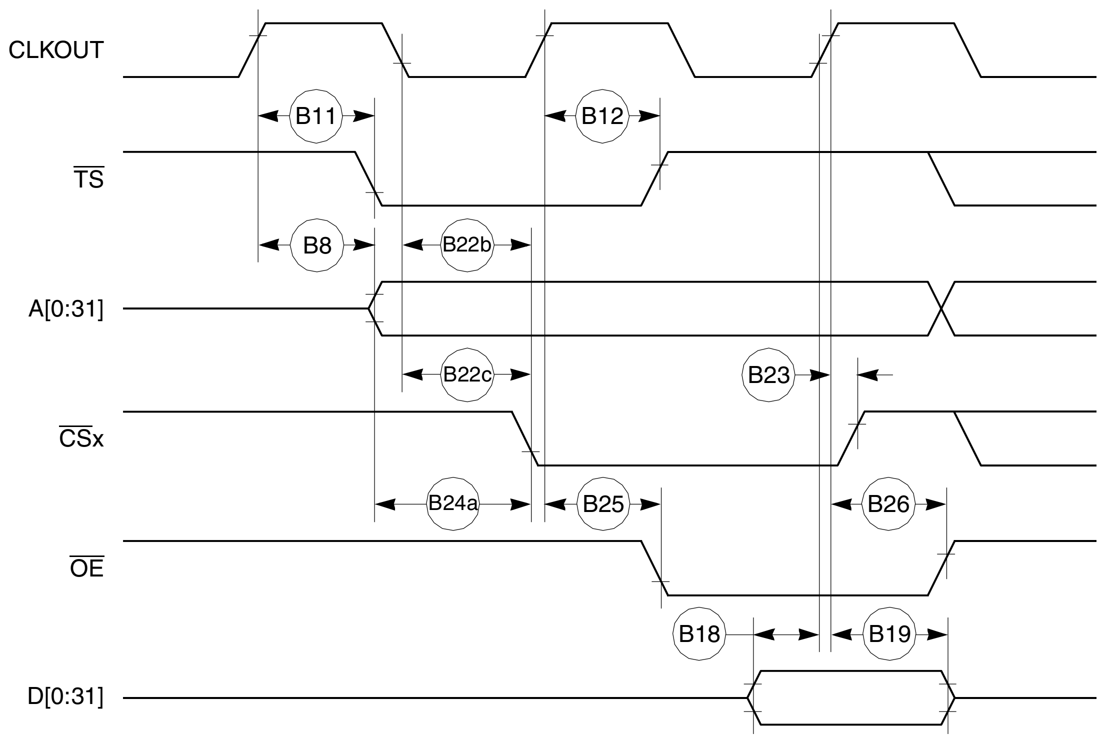


Figure 15. External Bus Read Timing (GPCM Controlled—TRLX = 0, ACS = 11)

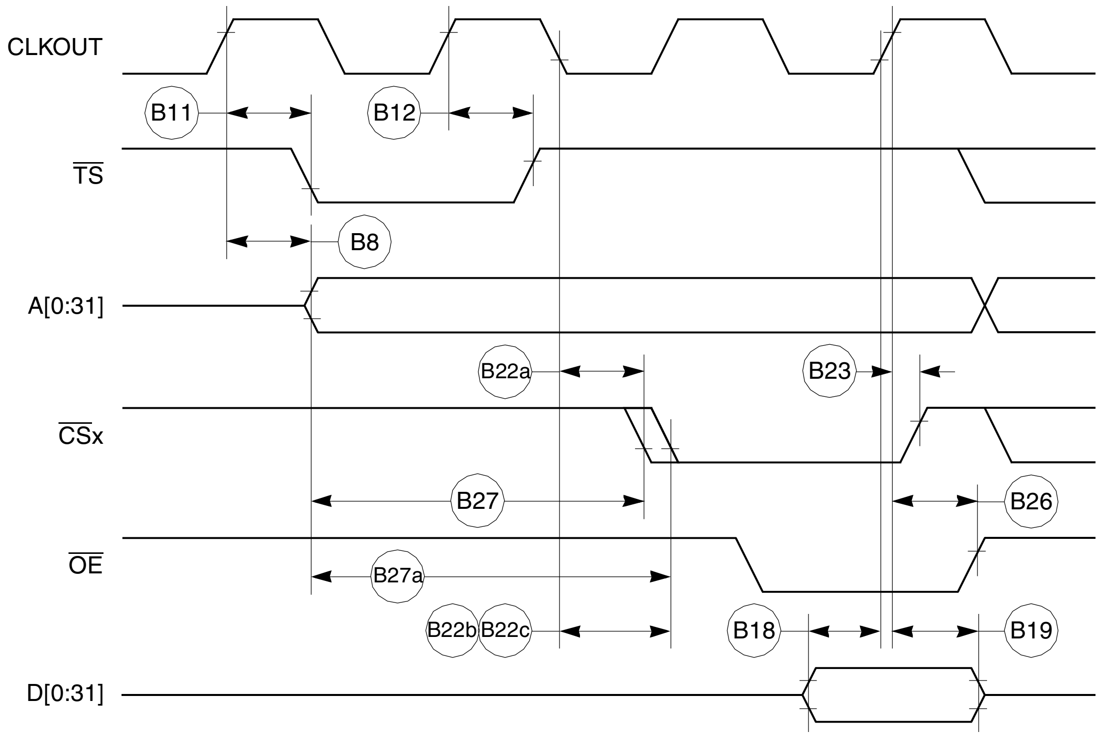


Figure 16. External Bus Read Timing (GPCM Controlled—TRLX = 1, ACS = 10, ACS = 11)

Figure 20 provides the timing for the external bus controlled by the UPM.

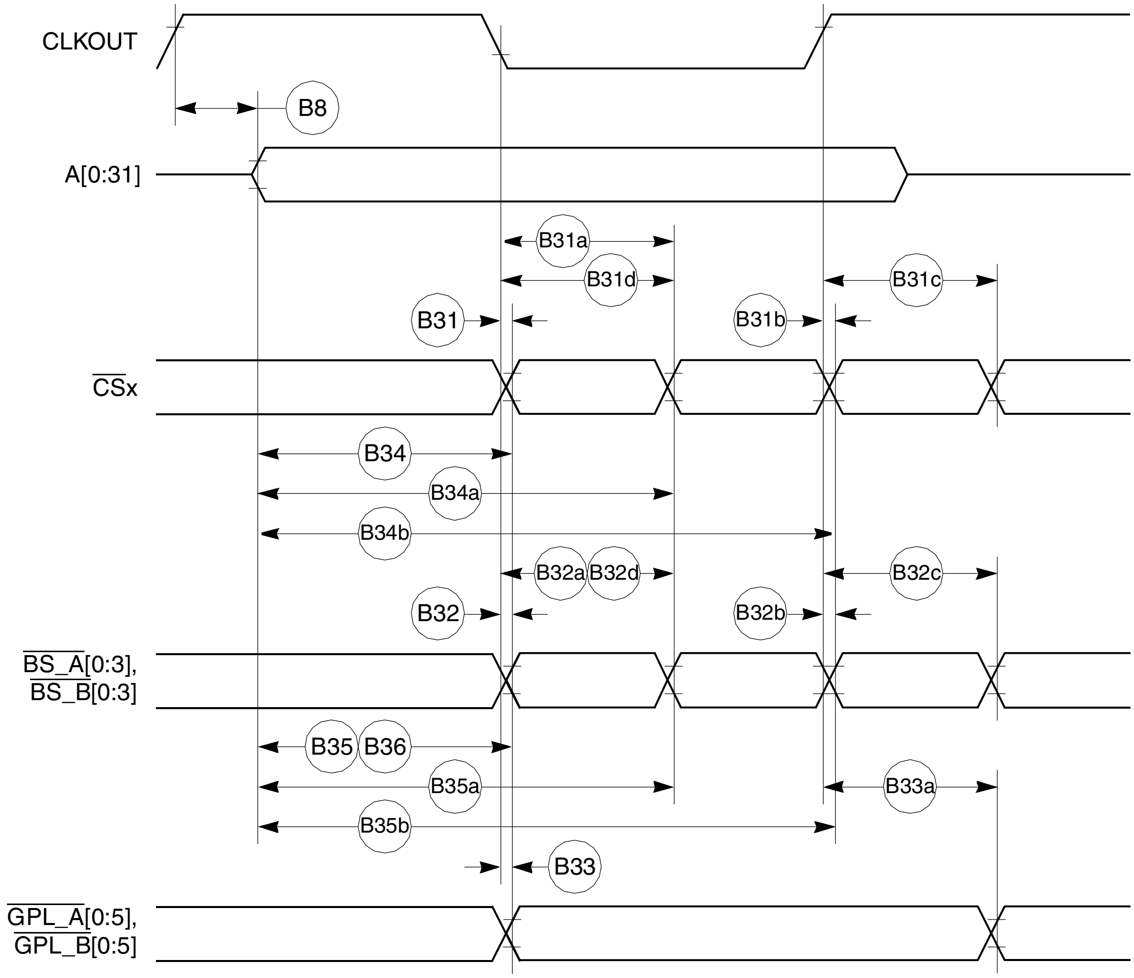


Figure 20. External Bus Timing (UPM-Controlled Signals)

Figure 21 provides the timing for the asynchronous asserted UPWAIT signal controlled by the UPM.

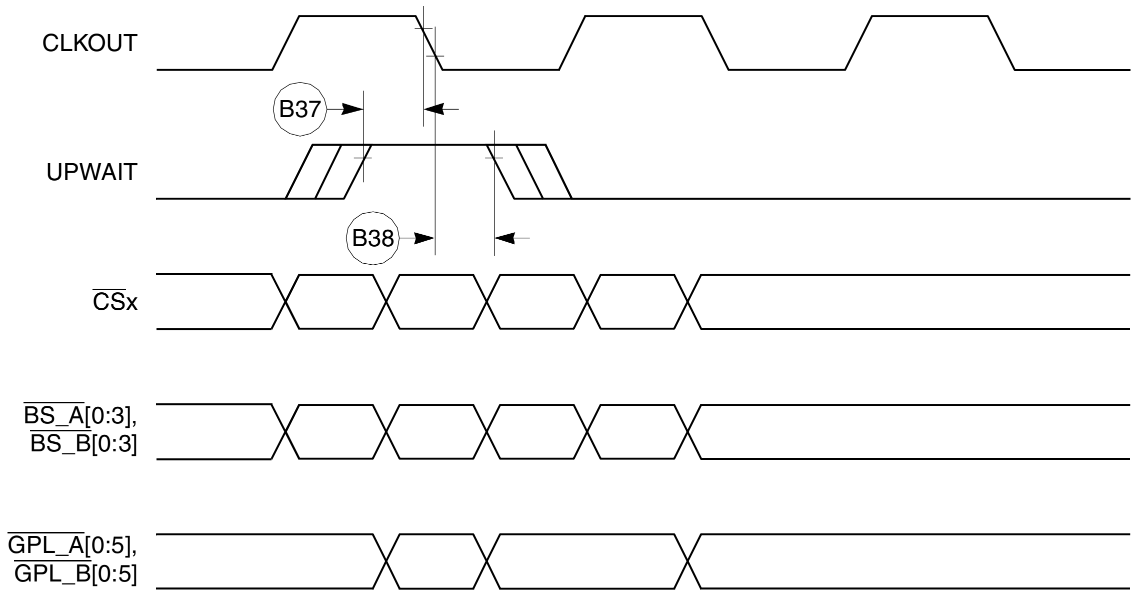


Figure 21. Asynchronous UPWAIT Asserted Detection in UPM-Handled Cycles Timing

Figure 22 provides the timing for the asynchronous negated UPWAIT signal controlled by the UPM.

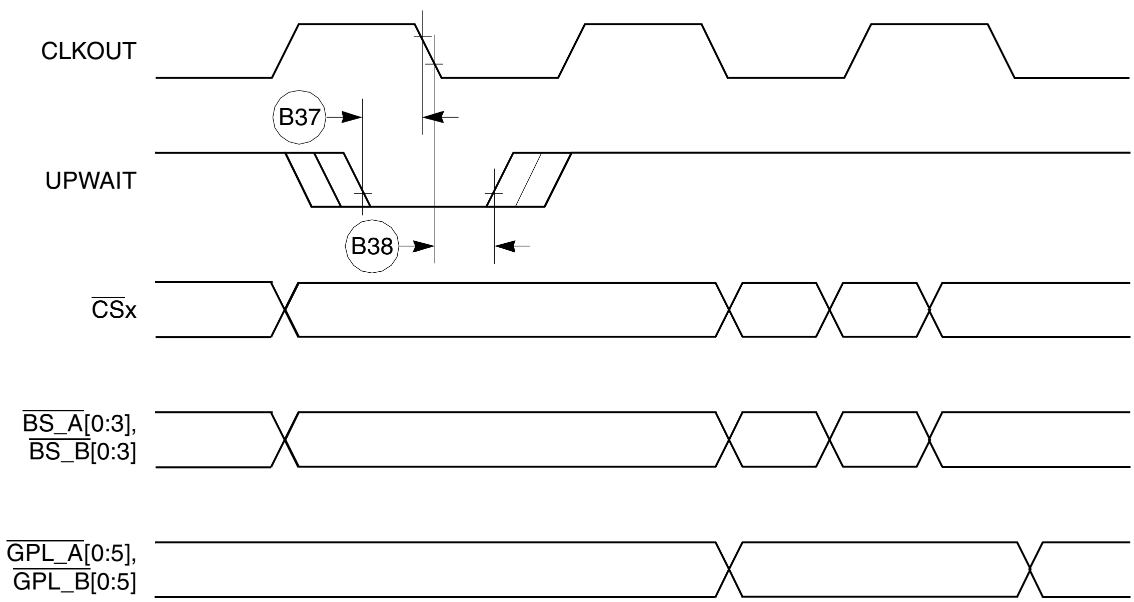


Figure 22. Asynchronous UPWAIT Negated Detection in UPM-Handled Cycles Timing

Table 10 provides the interrupt timing for the MPC885/MPC880.

Table 10. Interrupt Timing

Num	Characteristic[1]	All Frequencies		Unit
		Min	Max	
I39	$\overline{IRQ}$x valid to CLKOUT rising edge (setup time)	6.00		ns
I40	$\overline{IRQ}$x hold time after CLKOUT	2.00		ns
I41	$\overline{IRQ}$x pulse width low	3.00		ns
I42	$\overline{IRQ}$x pulse width high	3.00		ns
I43	$\overline{IRQ}$x edge-to-edge time	$4 \times T_{CLOCKOUT}$		—

[1] The I39 and I40 timings describe the testing conditions under which the $\overline{IRQ}$ lines are tested when being defined as level sensitive. The $\overline{IRQ}$ lines are synchronized internally and do not have to be asserted or negated with reference to the CLKOUT. The I41, I42, and I43 timings are specified to allow correct functioning of the $\overline{IRQ}$ lines detection circuitry and have no direct relation with the total system interrupt latency that the MPC885/MPC880 is able to support.

Figure 26 provides the interrupt detection timing for the external level-sensitive lines.

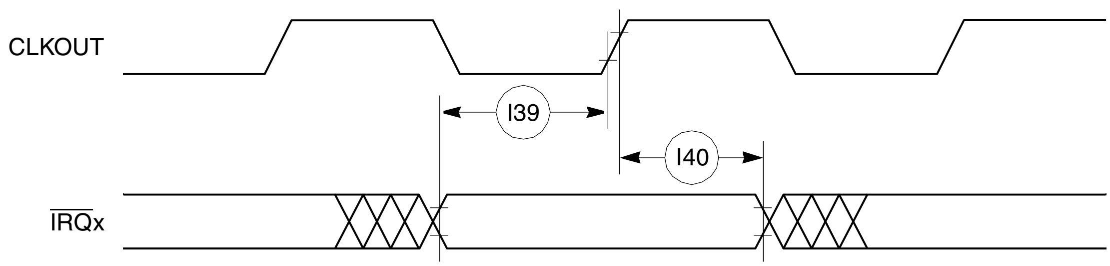


Figure 26. Interrupt Detection Timing for External Level Sensitive Lines

Figure 27 provides the interrupt detection timing for the external edge-sensitive lines.

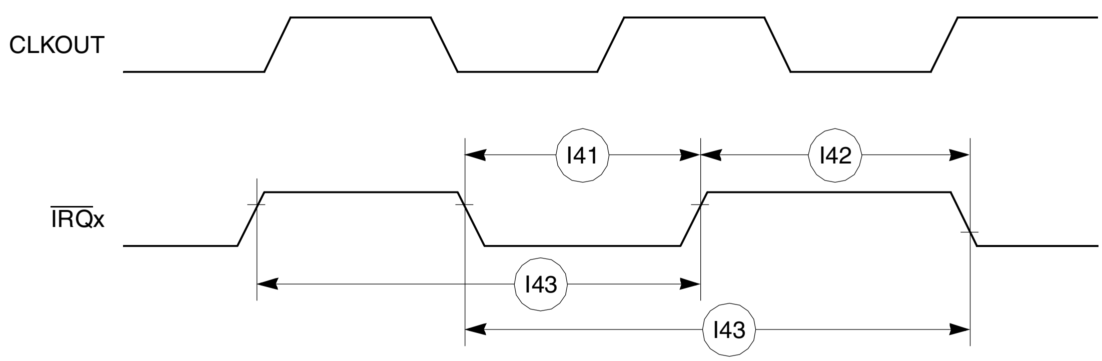


Figure 27. Interrupt Detection Timing for External Edge Sensitive Lines

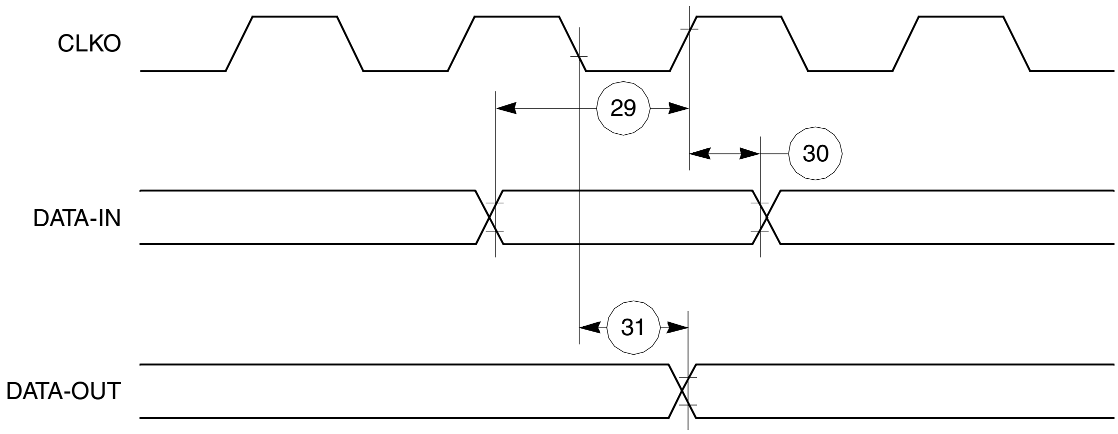


Figure 46. Parallel I/O Data-In/Data-Out Timing Diagram

12.2 Port C Interrupt AC Electrical Specifications

Table 17 provides the timings for port C interrupts.

Table 17. Port C Interrupt Timing

Num	Characteristic	33.34 MHz		Unit
		Min	Max	
35	Port C interrupt pulse width low (edge-triggered mode)	55	—	ns
36	Port C interrupt minimum time between active edges	55	—	ns

Figure 47 shows the port C interrupt detection timing.

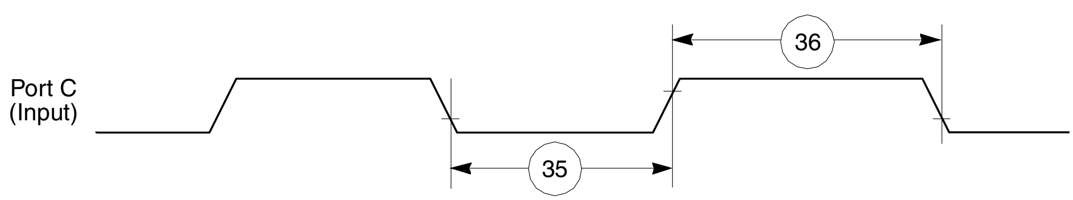


Figure 47. Port C Interrupt Detection Timing

Table 21. SI Timing (continued)

Num	Characteristic	All Frequencies		Unit
		Min	Max	
76	L1RXD valid to L1CLK edge (L1RXD setup time)	17.00	—	ns
77	L1CLK edge to L1RXD invalid (L1RXD hold time)	13.00	—	ns
78	L1CLK edge to L1ST(1–4) valid[4]	10.00	45.00	ns
78A	L1SYNC valid to L1ST(1–4) valid	10.00	45.00	ns
79	L1CLK edge to L1ST(1–4) invalid	10.00	45.00	ns
80	L1CLK edge to L1TXD valid	10.00	55.00	ns
80A	L1TSYNC valid to L1TXD valid[4]	10.00	55.00	ns
81	L1CLK edge to L1TXD high impedance	0.00	42.00	ns
82	L1RCLK, L1TCLK frequency (DSC =1)	—	16.00 or SYNCCLK/2	MHz
83	L1RCLK, L1TCLK width low (DSC =1)	P + 10	—	ns
83a	L1RCLK, L1TCLK width high (DSC = 1)[3]	P + 10	—	ns
84	L1CLK edge to L1CLKO valid (DSC = 1)	—	30.00	ns
85	$\overline{\text{L1RQ}}$ valid before falling edge of L1TSYNC[4]	1.00	—	L1TCLK
86	L1GR setup time[2]	42.00	—	ns
87	L1GR hold time	42.00	—	ns
88	L1CLK edge to L1SYNC valid (FSD = 00) CNT = 0000, BYT = 0, DSC = 0)	—	0.00	ns

1 The ratio SyncCLK/L1RCLK must be greater than 2.5/1.
2 These specs are valid for IDL mode only.
3 Where P = 1/CLKOUT. Thus for a 25-MHz CLKO1 rate, P = 40 ns.
4 These strobes and TxD on the first bit of the frame become valid after L1CLK edge or L1SYNC, whichever comes later.

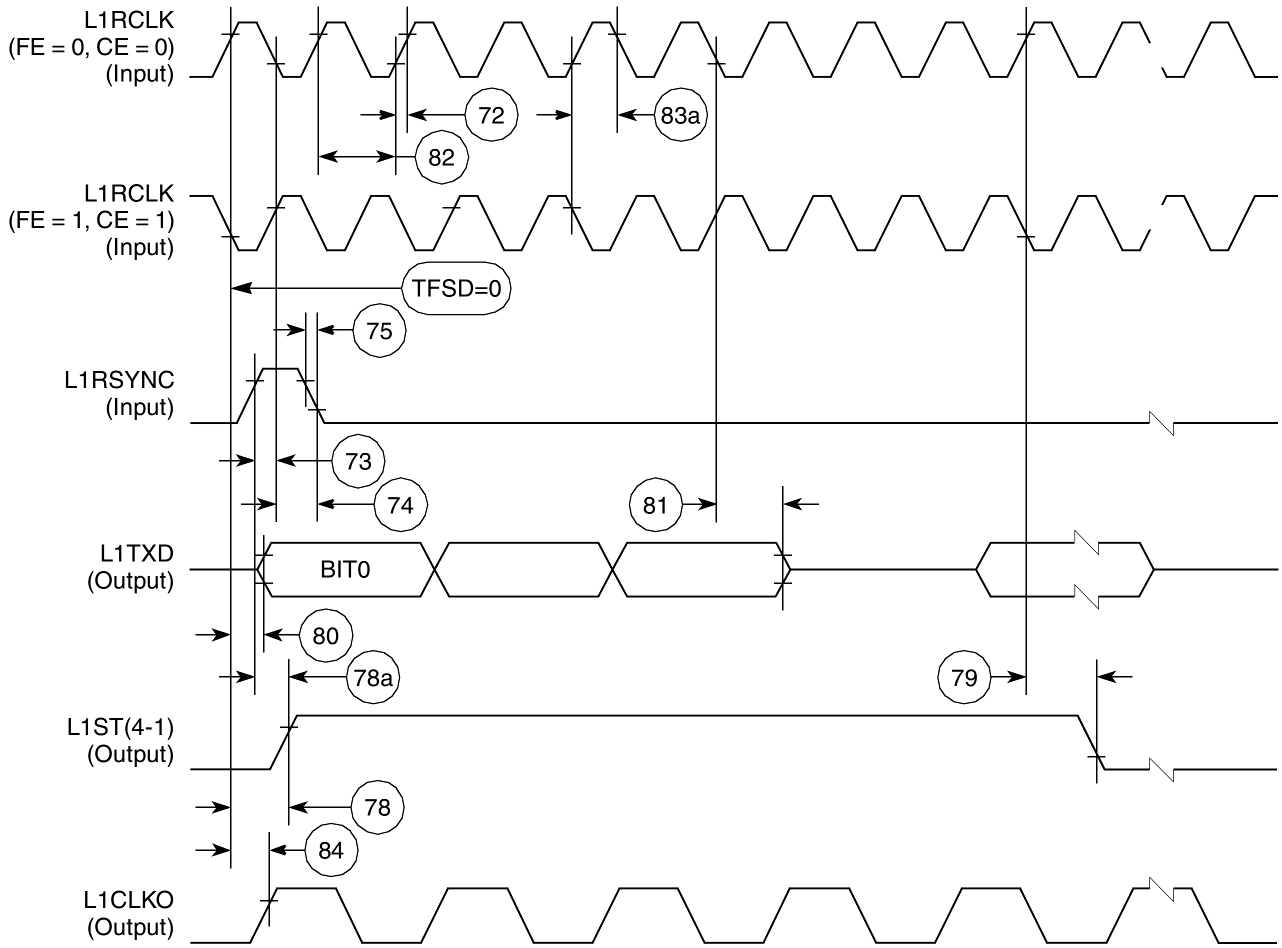


Figure 57. SI Transmit Timing with Double Speed Clocking (DSC = 1)

12.7 SCC in NMSI Mode Electrical Specifications

Table 22 provides the NMSI external clock timing.

Table 22. NMSI External Clock Timing

Num	Characteristic	All Frequencies		Unit
		Min	Max	
100	RCLK1 and TCLK1 width high[1]	1/SYNCCLK	—	ns
101	RCLK1 and TCLK1 width low	1/SYNCCLK + 5	—	ns
102	RCLK1 and TCLK1 rise/fall time	—	15.00	ns
103	TXD1 active delay (from TCLK1 falling edge)	0.00	50.00	ns
104	$\overline{\text{RTS1}}$ active/inactive delay (from TCLK1 falling edge)	0.00	50.00	ns
105	$\overline{\text{CTS1}}$ setup time to TCLK1 rising edge	5.00	—	ns
106	RXD1 setup time to RCLK1 rising edge	5.00	—	ns
107	RXD1 hold time from RCLK1 rising edge[2]	5.00	—	ns
108	$\overline{\text{CD1}}$ setup time to RCLK1 rising edge	5.00	—	ns

1 The ratios SyncCLK/RCLK1 and SyncCLK/TCLK1 must be greater than or equal to 2.25/1.
2 Also applies to $\overline{\text{CD}}$ and $\overline{\text{CTS}}$ hold time when they are used as external sync signals.

Table 23 provides the NMSI internal clock timing.

Table 23. NMSI Internal Clock Timing

Num	Characteristic	All Frequencies		Unit
		Min	Max	
100	RCLK1 and TCLK1 frequency[1]	0.00	SYNCCLK/3	MHz
102	RCLK1 and TCLK1 rise/fall time	—	—	ns
103	TXD1 active delay (from TCLK1 falling edge)	0.00	30.00	ns
104	$\overline{\text{RTS1}}$ active/inactive delay (from TCLK1 falling edge)	0.00	30.00	ns
105	$\overline{\text{CTS1}}$ setup time to TCLK1 rising edge	40.00	—	ns
106	RXD1 setup time to RCLK1 rising edge	40.00	—	ns
107	RXD1 hold time from RCLK1 rising edge[2]	0.00	—	ns
108	$\overline{\text{CD1}}$ setup time to RCLK1 rising edge	40.00	—	ns

1 The ratios SyncCLK/RCLK1 and SyncCLK/TCLK1 must be greater than or equal to 3/1.
2 Also applies to $\overline{\text{CD}}$ and $\overline{\text{CTS}}$ hold time when they are used as external sync signals

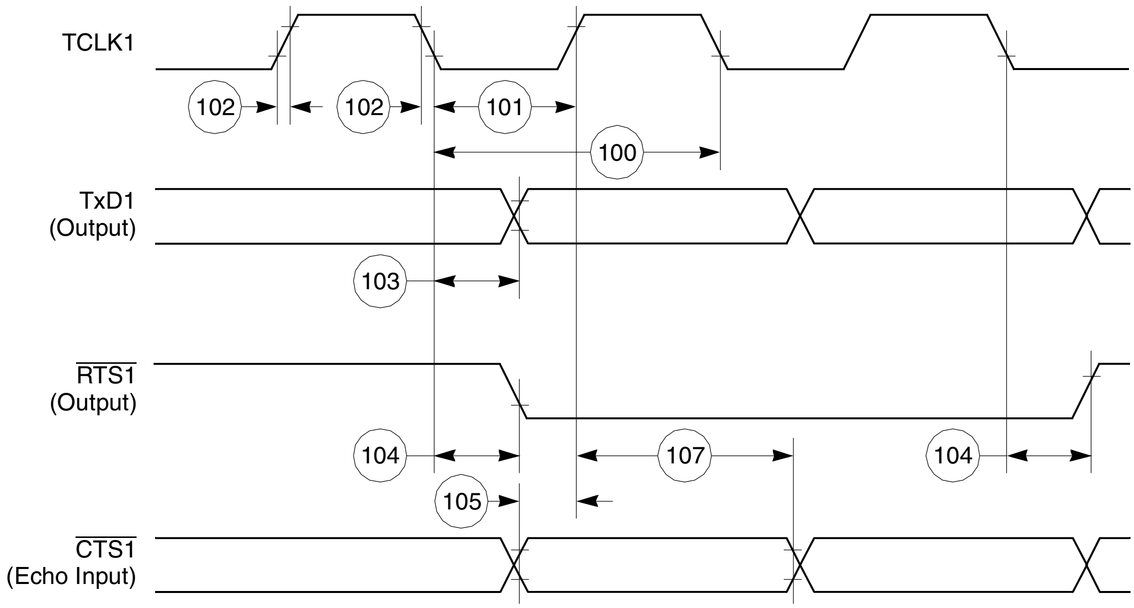


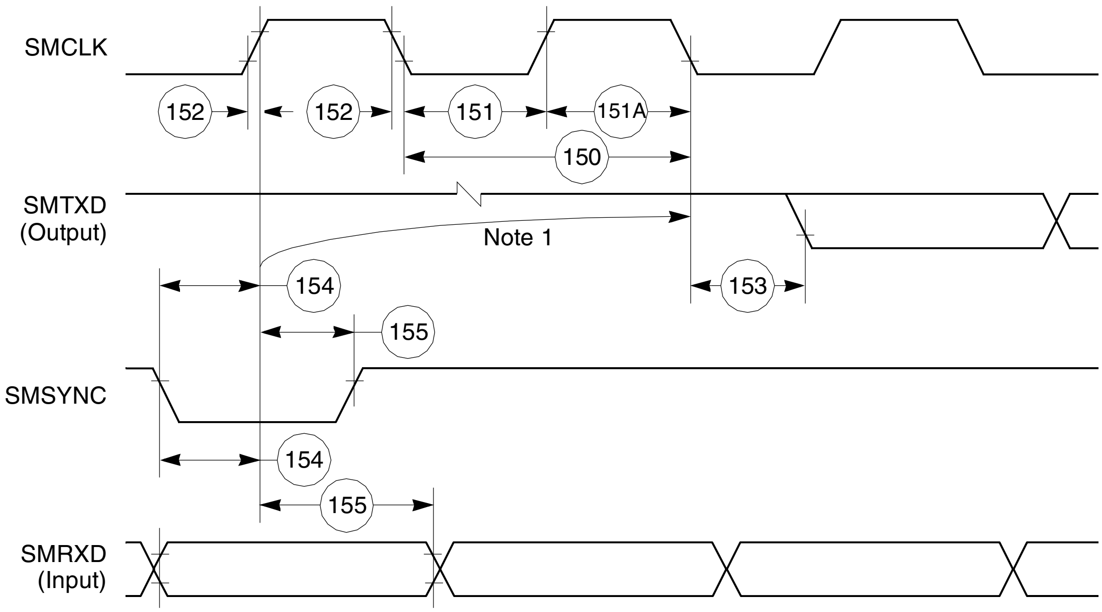
Figure 61. HDLC Bus Timing Diagram

12.8 Ethernet Electrical Specifications

Table 24 provides the Ethernet timings as shown in Figure 62 through Figure 64.

Table 24. Ethernet Timing

Num	Characteristic	All Frequencies		Unit
		Min	Max	
120	CLSN width high	40	—	ns
121	RCLK1 rise/fall time	—	15	ns
122	RCLK1 width low	40	—	ns
123	RCLK1 clock period[1]	80	120	ns
124	RXD1 setup time	20	—	ns
125	RXD1 hold time	5	—	ns
126	RENA active delay (from RCLK1 rising edge of the last data bit)	10	—	ns
127	RENA width low	100	—	ns
128	TCLK1 rise/fall time	—	15	ns
129	TCLK1 width low	40	—	ns
130	TCLK1 clock period[1]	99	101	ns
131	TXD1 active delay (from TCLK1 rising edge)	—	50	ns
132	TXD1 inactive delay (from TCLK1 rising edge)	6.5	50	ns
133	TENA active delay (from TCLK1 rising edge)	10	50	ns



Note:
1. This delay is equal to an integer number of character-length clocks.

Figure 65. SMC Transparent Timing Diagram

12.10 SPI Master AC Electrical Specifications

Table 26 provides the SPI master timings as shown in Figure 66 and Figure 67.

Table 26. SPI Master Timing

Num	Characteristic	All Frequencies		Unit
		Min	Max	
160	MASTER cycle time	4	1024	t_{cyc}
161	MASTER clock (SCK) high or low time	2	512	t_{cyc}
162	MASTER data setup time (inputs)	15	—	ns
163	Master data hold time (inputs)	0	—	ns
164	Master data valid (after SCK edge)	—	10	ns
165	Master data hold time (outputs)	0	—	ns
166	Rise time output	—	15	ns
167	Fall time output	—	15	ns

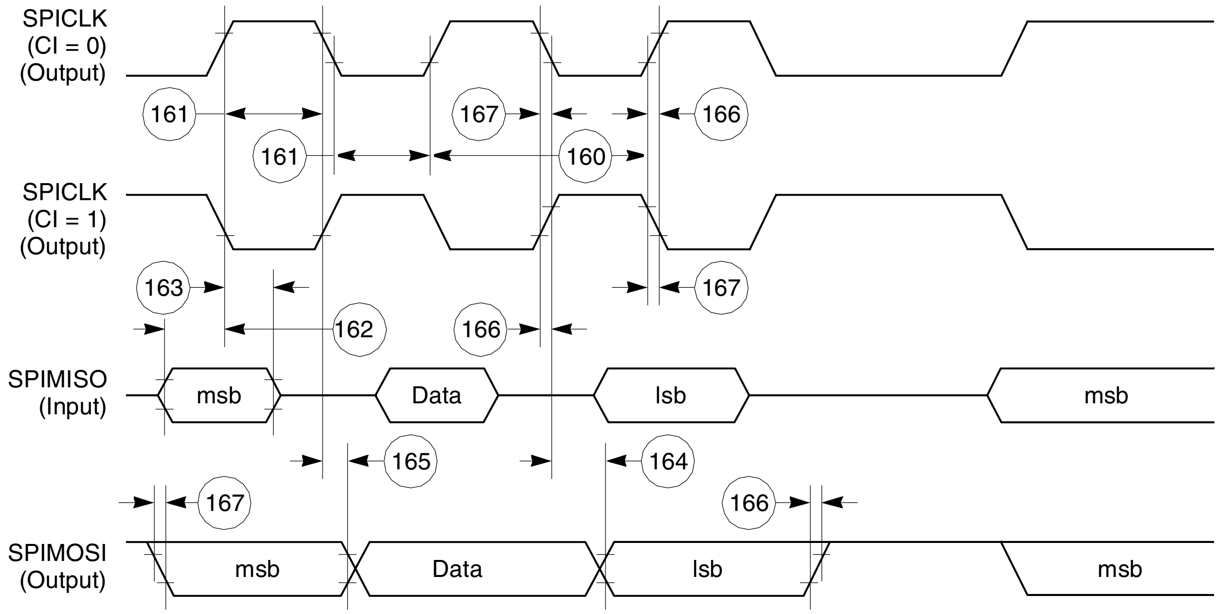


Figure 66. SPI Master (CP = 0) Timing Diagram

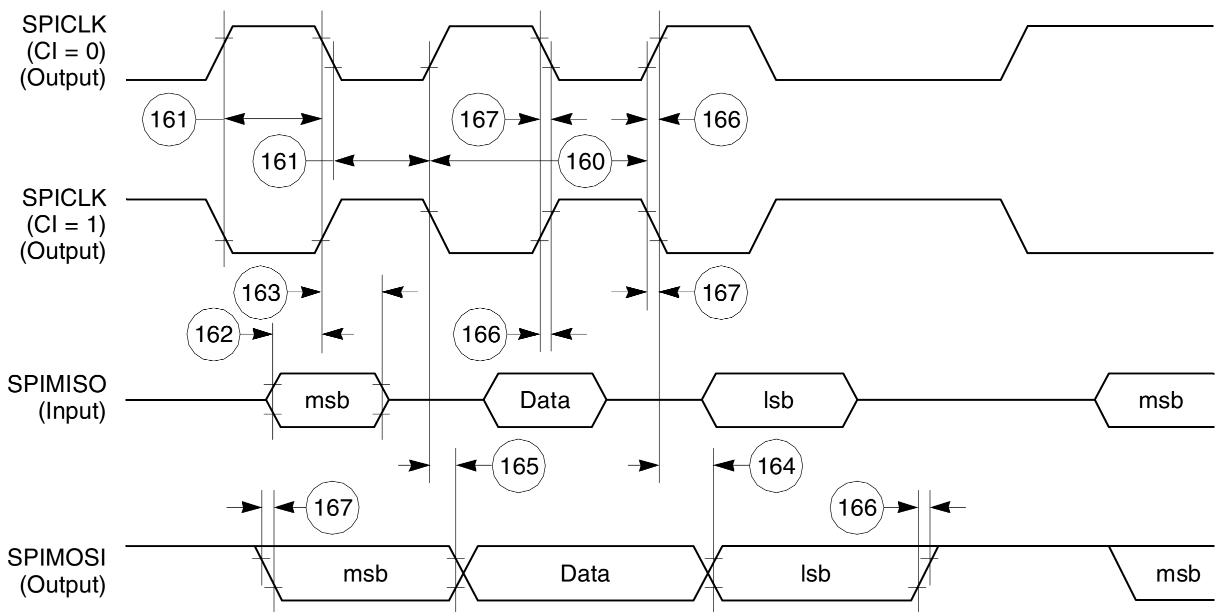


Figure 67. SPI Master (CP = 1) Timing Diagram

14 USB Electrical Characteristics

This section provides the AC timings for the USB interface.

14.1 USB Interface AC Timing Specifications

The USB Port uses the transmit clock on SCC1. Table 33 lists the USB interface timings.

Table 33. USB Interface AC Timing Specifications

Name	Characteristic	All Frequencies		Unit
		Min	Max	
US1	USBCLK frequency of operation[1] Low speed Full speed	6 48		MHz MHz
US4	USBCLK duty cycle (measured at 1.5 V)	45	55	%

[1] USBCLK accuracy should be ±500 ppm or better. USBCLK may be stopped to conserve power.

15 FEC Electrical Characteristics

This section provides the AC electrical specifications for the fast Ethernet controller (FEC). Note that the timing specifications for the MII signals are independent of system clock frequency (part speed designation). Also, MII signals use TTL signal levels compatible with devices operating at either 5.0 or 3.3 V.

15.1 MII and Reduced MII Receive Signal Timing

The receiver functions correctly up to a MII_RX_CLK maximum frequency of 25 MHz + 1%. The reduced MII (RMII) receiver functions correctly up to a RMII_REFCLK maximum frequency of 50 MHz + 1%. There is no minimum frequency requirement. In addition, the processor clock frequency must exceed the MII_RX_CLK frequency – 1%.

Table 34 provides information on the MII and RMII receive signal timing.

Table 34. MII Receive Signal Timing

Num	Characteristic	Min	Max	Unit
M1	MII_RXD[3:0], MII_RX_DV, MII_RX_ERR to MII_RX_CLK setup	5	—	ns
M2	MII_RX_CLK to MII_RXD[3:0], MII_RX_DV, MII_RX_ER hold	5	—	ns
M3	MII_RX_CLK pulse width high	35%	65%	MII_RX_CLK period
M4	MII_RX_CLK pulse width low	35%	65%	MII_RX_CLK period
M1_RMII	RMII_RXD[1:0], RMII_CRS_DV, RMII_RX_ERR to RMII_REFCLK setup	4	—	ns
M2_RMII	RMII_REFCLK to RMII_RXD[1:0], RMII_CRS_DV, RMII_RX_ERR hold	2	—	ns

Figure 73 shows MII receive signal timing.

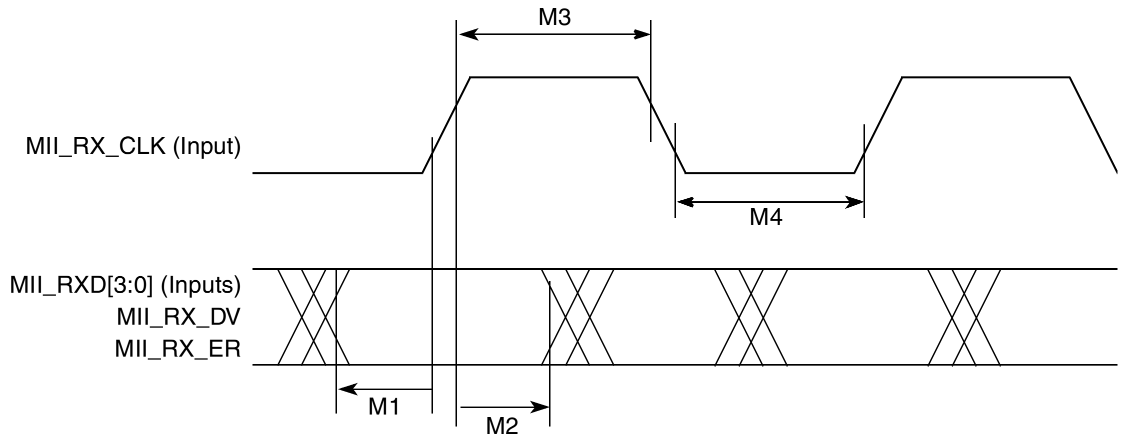


Figure 73. MII Receive Signal Timing Diagram

15.2 MII and Reduced MII Transmit Signal Timing

The transmitter functions correctly up to a MII_TX_CLK maximum frequency of 25 MHz + 1%. The RMII transmitter functions correctly up to a RMII_REFCLK maximum frequency of 50 MHz + 1%. There is no minimum frequency requirement. In addition, the processor clock frequency must exceed the MII_TX_CLK frequency – 1%.

Table 35 provides information on the MII and RMII transmit signal timing.

Table 35. MII Transmit Signal Timing

Num	Characteristic	Min	Max	Unit
M5	MII_TX_CLK to MII_TXD[3:0], MII_TX_EN, MII_TX_ER invalid	5	—	ns
M6	MII_TX_CLK to MII_TXD[3:0], MII_TX_EN, MII_TX_ER valid	—	25	ns
M20_RMII	RMII_TXD[1:0], RMII_TX_EN to RMII_REFCLK setup	4	—	ns
M21_RMII	RMII_TXD[1:0], RMII_TX_EN data hold from RMII_REFCLK rising edge	2	—	ns
M7	MII_TX_CLK and RMII_REFCLK pulse width high	35%	65%	MII_TX_CLK or RMII_REFCLK period
M8	MII_TX_CLK and RMII_REFCLK pulse width low	35%	65%	MII_TX_CLK or RMII_REFCLK period

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USA/Europe or Locations Not Listed:
Freescale Semiconductor, Inc.
Technical Information Center, EL516
2100 East Elliot Road
Tempe, Arizona 85284
1-800-521-6274 or
+1-480-768-2130
www.freescale.com/support

Europe, Middle East, and Africa:
Freescale Halbleiter Deutschland GmbH
Technical Information Center
Schatzbogen 7
81829 Muenchen, Germany
+44 1296 380 456 (English)
+46 8 52200080 (English)
+49 89 92103 559 (German)
+33 1 69 35 48 48 (French)
www.freescale.com/support

Japan:
Freescale Semiconductor Japan Ltd.
Headquarters
ARCO Tower 15F
1-8-1, Shimo-Meguro, Meguro-ku
Tokyo 153-0064
Japan
0120 191014 or
+81 3 5437 9125
support.japan@freescale.com

Asia/Pacific:
Freescale Semiconductor China Ltd.
Exchange Building 23F
No. 118 Jianguo Road
Chaoyang District
Beijing 100022
China
+86 10 5879 8000
support.asia@freescale.com

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Literature Distribution Center
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Fax: +1-303-675-2150
LDCForFreescaleSemiconductor
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